

Title (en)
Sample processing apparatus

Title (de)
Vorrichtung zur Behandlung von Proben

Title (fr)
Appareil de traitement d'échantillons

Publication
EP 0751552 A1 19970102 (EN)

Application
EP 96112707 A 19900207

Priority
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• JP 4297689 A 19890227

Abstract (en)
A method of processing a sample comprises etching the sample by means of an etching plasma, and then treating the sample by means of a second plasma, to remove residual corrosive compounds formed by the etching plasma. Removal of the residual corrosive compounds and prevention of corrosion is much improved by contacting the surface of the sample after the second plasma treatment with at least one liquid in order to effect at least one of (a) removal of the residual corrosive compounds and (b) passivation of said surface exposed by steps, and drying the sample. <IMAGE>

IPC 1-7
H01L 21/00; **H01J 37/18**

IPC 8 full level
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CPC (source: EP KR US)
C23F 4/00 (2013.01 - EP US); **H01J 37/185** (2013.01 - EP US); **H01L 21/306** (2013.01 - KR); **H01L 21/32136** (2013.01 - EP US); **H01L 21/67017** (2013.01 - EP US); **H01L 21/67069** (2013.01 - EP US); **H01L 21/67161** (2013.01 - EP US); **H01L 21/67167** (2013.01 - EP US); **H01L 21/67207** (2013.01 - EP US); **H01L 21/67745** (2013.01 - EP US); **H01L 21/67748** (2013.01 - EP US); **H01L 21/67751** (2013.01 - EP US)

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• [A] PATENT ABSTRACTS OF JAPAN vol. 004, no. 117 (E - 022) 20 August 1980 (1980-08-20)
• [A] DATABASE WPI Section PQ Week 8840, Derwent World Patents Index; Class P55, AN 88-281027, XP002016756
• [A] DATABASE WPI Section Ch Week 8832, Derwent World Patents Index; Class M13, AN 88-223596, XP002016757

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